K-VCO-2325

Previously named LE-Ka1310301

GaAs PHEMT MMIC Voltage Controlled Oscillator 23.5 - 24.8 GHz

#### Overview

K-VCO-2325 is a bare die Voltage Controlled Oscillator MMIC, with integrated subharmonic mixer, covering frequencies from 23.5GHz to 24.8GHz, by using a tuning voltage between 0 and 1.6V. This MMIC provides a constant 15dBm output power over all tuning voltages, running from a 3V supply with currents <60mA. By applying a signal at F/2 from the required operational frequency (F) to the integrated subharmonic mixer, and provides an additional output signal which is proportional in frequency to F and which can be introduced into a PLL for frequency stability.

The MMIC is fully passivated for additional protection and has all bond pads and backside gold plated. The MMIC is compatible with precision die attach methods, as well as thermo-compression and thermosonic wire bonding, making it ideal for MCM and hybrid microcircuit applications. All data shown is measured with the chip in a 50 Ohm environment and contacted with RF probes.

#### **Features**

- 23.5 24.8GHz.
- 15dBm output power.
- Integrated sub-harmonic mixer for phase stability.

## **Applications**

- High speed data communications.
- · Space communications.
- IOT.
- Security.

# **Specification Overview**

Parameter	Min.	Тур.	Max.	Units
Output Frequency (Fout)	23.5		24.8	GHz
Output Power		15		dBm
Reference / LO Frequency	10.8	12	13.6	GHz
PLL / IF Frequency	0		3.2	GHz
Phase Noise @100KHz Offset (1Hz Bandwidth)		-100		dBc/Hz
Supply Voltage, VOSC, VAMP		3		V
Tuning Voltage	0	0.6	1.6	V
Current		56		mA

#### Notes

The tests indicated have all been performed with 100pF de-coupling capacitors on all bias pads.

All tests are carried out at 25°C.

## **Absolute Maximum Ratings**

Parameter	Rating		
Supply Voltage (VOSC, VAMP)	5V		
Tuning Voltage	0 – 2V		
Storage Temperature	−65°C to +150°C		
Channel Temperature	+150°C		
Operating Temperature	-40°C to +85°C		



ESD (electrostatic discharge) sensitive device. Charged devices and circuit boards can discharge without detection. Although this product features proprietary protection circuitry, damage may occur on devices subjected to ESD. Proper ESD precautions should be taken to avoid performance degradation or loss of functionality.

Arralis	K band Datasheet	K-VCO-2325	Issue date: 30 April 21	DOC REV 3	Page 2 of 9

#### **Measured Performance Data**



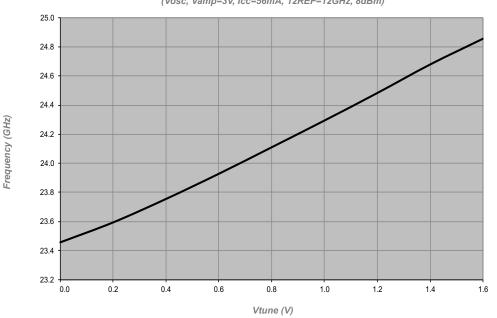


Figure 1
Output Frequency



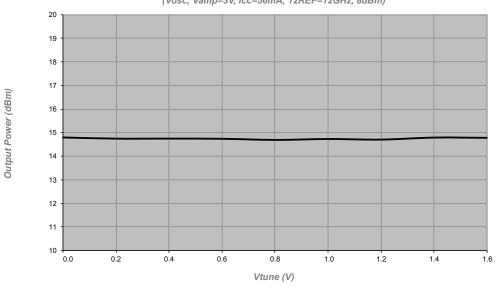


Figure 2
Output Power

Arralis	K band Datasheet	K-VCO-2325	Issue date: 30 April 21	DOC REV 3	Page 3 of 9	

#### **Measured Performance Data**

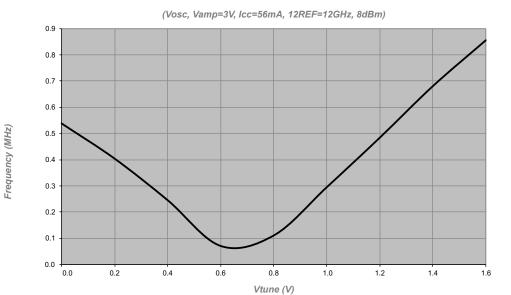
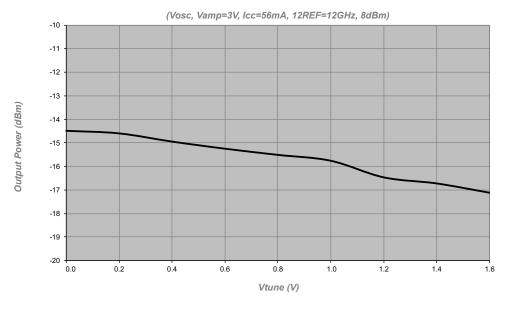


Figure 3
PLL Output Frequency



Figu	re 4
PLL	Output Power

#### **Measured Performance Data**

Current (mA)



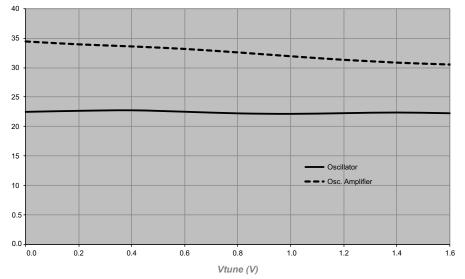
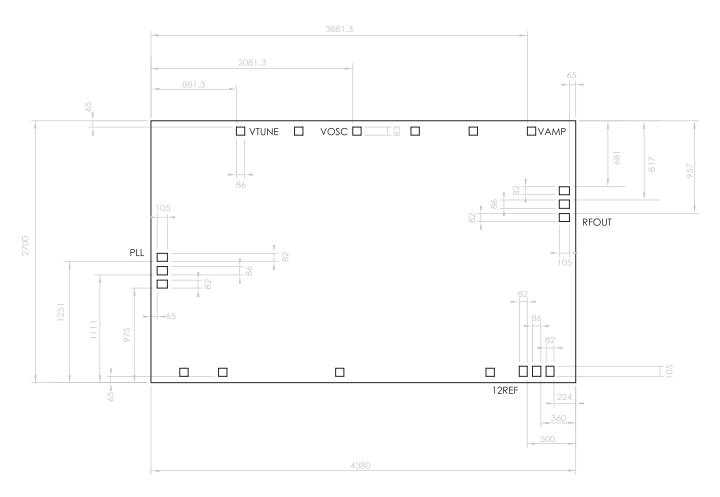


Figure 5
Current Draw

Arralis K band Datasheet K-VCO-2325 Issue date: 30 April 21 DOC REV 3 Page 5 of 9

## **Outline Drawing**



#### **Notes**

- 1. All dimensions are in um.
- 2. Typical DC bond pads are 80um square.
- 3. RF bond pads are 105 x 80um.
- 4. All pads have gold metalisation.
- 5. Gold backside metalisation.
- 6. Backside metal is ground.
- 7. Connections are not required for unlabelled bond pads.
- 8. Die thickness is 100um

#### **Die Packing Information**

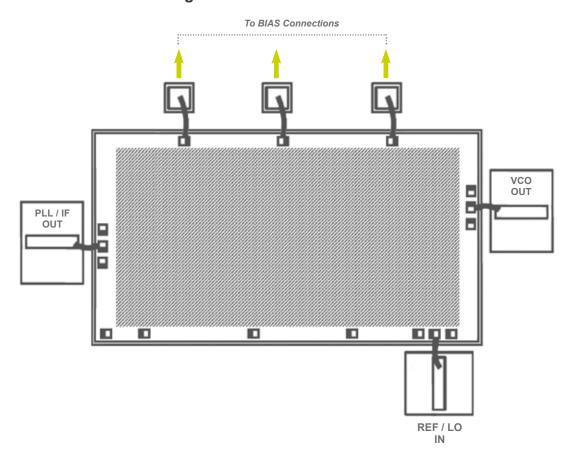
All die are delivered using gel-paks unless otherwise requested.

Arralis K band Datasheet	K-VCO-2325	Issue date: 30 April 21	DOC REV 3	Page 6 of 9	
--------------------------	------------	-------------------------	-----------	-------------	--

# **Pad Descriptions**

Name	Description
RFOUT	Output RF pad for oscillator frequency. This pad is AC coupled.
VTUNE	Frequency tuning voltage pad.
vosc	Bias pad for oscillator circuit.
VAMP	Bias pad for amplifier circuit.
12REF	Input pad for 12GHz reference or LO signal. This pad is AC coupled.

# **Connection Configurations**



Arralis K band Datasheet	C-VCO-2325	Issue date: 30 April 21	DOC REV 3	Page 7 of 9	
--------------------------	------------	-------------------------	-----------	-------------	--

### **General Notes on Assembly**

Die should be mounted on conductive material such as gold-plated metal to provide a good ground and suitable heat sink, if necessary.

- 1. Attaching the die using Au/Sn preforms is preferable. The Eutectic melt for Au/Sn occurs at approximately 280°C so the die (plus mount and preform) is initially heated up to 180°C and then it is heated for approximately 10 seconds to 280°C using a nitrogen heat gun. The device will survive 10 seconds at this temperature. The static breakdown for GaAs devices is approximately 330°C.
- 2. Pure, dry nitrogen should be used as the heat source.
- 3. If the devices cannot be lifted/ placed by a vacuum device, then ESD die-lifting tweezers are preferable.
- Supply lines should be decoupled with 100pF capacitors. Larger planar capacitors could be used if available.
- 5. Aluminium wire must not be used.

#### Disclaimer

The information contained herein is believed to be reliable; however, Arralis makes no warranties regarding the information and assumes no responsibility or liability whatsoever for the use of the information contained herein. All information is subject to change without notice, therefore customers should obtain the latest relevant information before placing orders for Arralis products. The information contained herein does not grant, explicitly or implicitly, to any party any patent rights, licenses, or any other intellectual property rights.

This information does not constitute a warranty with respect to the product described, and Arralis disclaims any and all warranties either expressed or implied, relating to sale and/or use of Arralis products including liability or warranties relating to fitness for a particular purpose, consequential or incidental damages, merchantability, or infringement of any patent, copyright or other intellectual property right.

Without limiting the generality of the foregoing, Arralis products are not warranted or authorised for use as critical components in medical, life-saving, or life-sustaining applications, or other applications where a failure would reasonably be expected to cause severe personal injury or death.

Copyright 2021 © Arralis



©2021 Arralis Ltd. All rights reserved. Trademarks and registered trademarks are the property of their respective owners.

Arralis European Offices

t: +(44) 1793 239670 (UK) e: sales@arralis.com Arralis USA Office

+(1) 386 301 3249 (USA)

arralis.com e: emilie.wren@arralis.com

